## AMENDMENTS TO THE CLAIMS

Please cancel Claims 9, 14 and 15.

**LISTING OF CLAIMS**

1.-18. (cancelled)

19. (previously presented) An apparatus for forming an insert molding, comprising:

a die set having a cavity;

means for controlling a temperature of the die set;

a hold member movably provided on the die set for holding an insert in the cavity;

means for injecting molten resin into the cavity when the insert is held by the hold member;

means for separating the hold member from the insert at a given timing;

means for heating a surface of the hold member to a temperature higher than a temperature of an inner surface of the die set, the surface of the hold member and contacting the molten resin, the die-set inner surface being exposed in the cavity; and

a controller for activating the heating means simultaneous with or after the injection means injects the molten resin in to the cavity.

20. (previously presented) An apparatus as recited in claim 19, wherein the hold member comprises a heat feeding portion and a body covering the heat feeding portion.

21. (previously presented) An apparatus as recited in claim 20, wherein the heat feeding portion comprising a heating member which generates heat when being supplied with an electric current.

22. (previously presented) An apparatus as recited in claim 19, wherein the hold member comprises a heat generating member and a body, the heat generating member being made of an electrically-conductive ceramic, the body surrounding the heat generating member, the body being made of an insulating ceramic.

23. (previously presented) An apparatus as recited in claim 19, wherein an inner surface of the die set comprises means for facilitating cooling of a first region of the molten resin in the cavity relative to cooling of a second region of the molten resin in the cavity, the die-set inner surface being exposed in the cavity, the second region adjoining the hold member, the first region being more distant from the hold member than the first region is.

24. (previously presented) An apparatus as recited in claim 23, wherein the first region is thinner than the second region.

25. (previously presented) An apparatus as recited in claim 19, wherein the heating means comprises means for heating the hold member to a temperature equal to or higher than a melting point of the injected resin.